HOME | ABOUT ECM | CONTACT US | REQUEST SAMPLES | NEW PRODUCTS | UPCOMING EVENTS

MEMBRANE SWITCHES | HEATERS | BIOSENSORS | FLEX CIRCUITS | SOLAR CELLS | SURFACE MOUNT

SOLAR MODULES

DB-1538-2 2 part, flexible, 2 min @180°C cure 2 x 10-4 50 11,000 Dispense DB-1541-S Best damp heat conductivity stability on Sn and tin-silver ribbon, flexible, high peel strength 2 x 10-4 8 22,000 Dispense DB-1541-S3 Lower silver content (lower cost) than DB-1541-S with same reliability, conductivity 1 1 x 10-4 0 10,000 Dispense DB-1541-S3 High shear strength, moderate Tg Conductivity stability on tin and tin-silver ribbon 3 x 10-4 60 10,000 Dispense DB-1548-1 High shear strength, moderate Tg Conductivity stability on tin and tin-silver ribbon 4 x 10-4 110 20,000 Dispense DB-1548-1 Low cost version of DB-1548-1 DB-1548-1 DB-1548-1 Low cost, flexible, excellent damp heat performance on OSP treated copper. Same chemistry as DB-1548 DB-1548-1 DB-1588-1 Lowest cost, flexible, excellent damp heat performance on OSP treated copper. Same chemistry as DB-1588 DB-1588-1 Lowest cost, flexible, excellent damp heat performance on OSP treated copper. Same chemistry as DB-1588-1 Lowest cost, flexible, excellent damp heat performance on OSP treated copper. Same chemistry as DB-1588-1 Lowest cost, flexible, excellent damp heat performance on OSP treated copper. Same chemistry as DB-1588-1 Lowest cost, flexible, excellent damp heat performance on OSP treated copper. Same chemistry as DB-1588-1 DB-1588	Product Designation	Description	Resistivity (ohm*cm)	Tg (°C) Tan Delta	Viscosity cP (5.0s-1)	Application Method	
DB-1541-S Best damp heat conductivity stability on Sn and tin-silver ribbon, flexible, high peel strength DB-1541-S3 Lower silver content (lower cost) than DB-1541-S with same reliability, conductivity DB-1548-1 High shear strength, moderate Tg Conductivity stability on tin and tin-silver ribbon Thing Tg conductive adhesive developed for glass backed thin film stringing applications. Good damp heat stability on molybdenum Low Cost Conductive Adhesives DB-1590 Low cost, fast/snap cure. Designed for ribbon stringing for crystralline silicon or thin film cells DB-1548-LC Low cost version of DB-1548 series DB-1541-LTC Low temperature cure version (100C) for organic PV and other temperature cure version (100C) for organic PV and other temperature sensitive modules Fiexible, high peel strength, Damp heat stability on tin and OSP treated copper. Designed to cure during EVA lamination DB-1588 Low cost, flexible, excellent damp heat performance on OSP treated copper. Same chemistry as DB-1581 DB-1588-1 Lowest cost, flexible, excellent damp heat performance on OSP treated copper. Same chemistry as DB-1588 Cl-1031-7 High thixotropy high aspect ratio / fine line print Low thixotropy Easiest to print DC-1031-8 Low thixotropy Easiest to print DC-1031-8 Low thixotropy Easiest to print DS-1581-1581-1581-1581-1581-1581-1581-158	Conductive Ribbon/Stringer Attach Adhesives						
DB-1541-S ribbon, flexible, high peel strength DB-1541-S3 Lower silver content (lower cost) than DB-1541-S with same reliability, conductivity DB-1548-1 High shear strength, moderate Tg Conductivity stability on tin and tin-silver ribbon CA-100 High Tg conductive adhesive developed for glass backed thin film stringing applications. Good damp heat stability on molybdenum Low Cost Conductive Adhesives DB-1590 Low cost, fast/snap cure. Designed for ribbon stringing for crystrailline silicon or thin film cells DB-1548-LC Low cost version of DB-1548 series DB-1541-LTC Low temperature cure version (100C) for organic PV and other temperature sensitive modules Conductive Adhesives for Back Contact Applications Flexible, high peel strength, Damp heat stability on tin and OSP treated copper. Designed to cure during EVA lamination DB-1588 Low cost, flexible, excellent damp heat performance on OSP treated copper. Same chemistry as DB-1541 DB-1588-1 Conductive Grid Inks CI-1031-8 Low thixotropy Easlest to print 1.5 x 10-5 75 12,000 Dispense 2x 10-4 8 22,000 10,000 Dispense 2 x 10-4 110 20,000 Dispense 2 x 10-4 15 20,000 Dispense 2 x 10-4 50 17,000 Dispense 1 x 10-4 13 33,000 Stencil Print 1 x 10-4 13 33,000 Stencil Print 1 x 10-4 13 30,000 Stencil Print 1 x 10-4 13 30,000 Stencil Print 1 x 10-4 10 DB-1588-1 Low cost, flexible, excellent damp heat performance on OSP treated copper. Same chemistry as DB-1581 DB-1588-1 Low thixotropy high aspect ratio / fine line print Low thixotropy Hg aspect ratio / fine line print 1.5 x 10-5 75 20,000 Screen Print	DB-1538-2	2 part, flexible, 2 min @180°C cure	2 x 10-4	50	11,000	Dispense	
DB-1548-1 High shear strength, moderate Tg Conductivity stability on tin and tin-silver ribbon CA-100 High Tg conductive adhesive developed for glass backed thin film stringing applications. Good damp heat stability on molybdenum Low Cost Conductive Adhesives DB-1590 Low cost, fast/snap cure. Designed for ribbon stringing for crystralline silicon or thin film cells DB-1548-LC Low cost version of DB-1548 series 9x 10-4 50 17,000 Dispense DB-1541-LTC Low temperature cure version (100C) for organic PV and other temperature sensitive modules DB-1541 Flexible, high peel strength, Damp heat stability on tin and OSP treated copper. Designed to cure during EVA lamination DB-1588 Low cost, flexible, excellent damp heat performance on OSP treated copper. Same chemistry as DB-1588 CI-1031-7 High thixotropy high aspect ratio / fine line print 1.5 x 10-5 75 20,000 Screen Print CI-1031-8 Low thixotropy high aspect ratio / fine line print 1.5 x 10-5 75 12,000 Screen Print	DB-1541-S		2 x 10-4	8	22,000	Dispense	
DB-1548-1 on tin and tin-silver ribbon CA-100 High Tg conductive adhesive developed for glass backed thin film stringing applications. Good damp heat stability on molybdenum DB-1590 Low cost, fast/snap cure. Designed for ribbon stringing for crystralline silicon or thin film cells DB-1548-LC Low cost version of DB-1548 series 9x 10-4 62 30,000 Dispense DB-1541-LTC Low temperature cure version (100C) for organic PV and other temperature sensitive modules DB-1541 Low temperature sensitive modules Flexible, high peel strength, Damp heat stability on tin and OSP treated copper. Designed to cure during EVA lamination DB-1588 Low cost, flexible, excellent damp heat performance on OSP treated copper. Same chemistry as DB-1541 DB-1588-1 Low cost, flexible, excellent damp heat performance on OSP treated copper. Same chemistry as DB-1588 Conductive Grid Inks CI-1031-7 High thixotropy high aspect ratio / fine line print 1.5 x 10-5 75 20,000 Screen Print CI-1031-8 Low thixotropy Easiest to print 1.5 x 10-5 75 12,000 Screen Print	DB-1541-S3	` '	1 x 10-4	0	10,000	Dispense	
thin film stringing applications. Good damp heat stability on molybdenum Low Cost Conductive Adhesives DB-1590 Low cost, fast/snap cure. Designed for ribbon stringing for crystralline silicon or thin film cells DB-1548-LC Low cost version of DB-1548 series DB-1541-LTC Low temperature Cure Conductive Adhesives DB-1541-LTC Low temperature cure version (100C) for organic PV and other temperature sensitive modules DB-1541-LTC Conductive Adhesives for Back Contact Applications Flexible, high peel strength, Damp heat stability on tin and OSP treated copper. Designed to cure during EVA lamination DB-1588 Low cost, flexible, excellent damp heat performance on OSP treated copper. Same chemistry as DB-1541 DB-1588-1 Lowest cost, flexible, excellent damp heat performance on OSP treated copper. Same chemistry as DB-1588 CI-1031-7 High thixotropy high aspect ratio / fine line print Low thixotropy Easiest to print Low thix to the tribute at the total tablities and the tablities and the table and the tablities and the table and the table and	DB-1548-1		3 x 10-4	60	10,000	Dispense	
DB-1590 Low cost, fast/snap cure. Designed for ribbon stringing for crystralline silicon or thin film cells DB-1548-LC Low cost version of DB-1548 series DB-1548-LC Low temperature Cure Conductive Adhesives DB-1541-LTC Low temperature cure version (100C) for organic PV and other temperature sensitive modules DB-1541-LTC Conductive Adhesives for Back Contact Applications Flexible, high peel strength, Damp heat stability on tin and OSP treated copper. Designed to cure during EVA lamination DB-1588 Low cost, flexible, excellent damp heat performance on OSP treated copper. Same chemistry as DB-1541 DB-1588-1 Lowest cost, flexible, excellent damp heat performance on OSP treated copper. Same chemistry as DB-1588 CI-1031-7 High thixotropy high aspect ratio / fine line print 1.5 x 10-5 75 20,000 Screen Print CI-1031-8 Low thixotropy Easiest to print 1.5 x 10-5 75 12,000 Screen Print CI-1031-8	CA-100	thin film stringing applications. Good damp heat stability	4 x 10-4	110	20,000	Dispense	
DB-1590 for crystralline silicon or thin film cells DB-1548-LC Low cost version of DB-1548 series 9x 10-4 62 30,000 Dispense Low Temperature Cure Conductive Adhesives DB-1541-LTC Low temperature cure version (100C) for organic PV and other temperature sensitive modules Conductive Adhesives for Back Contact Applications Flexible, high peel strength, Damp heat stability on tin and OSP treated copper. Designed to cure during EVA lamination DB-1541 DB-1588 Low cost, flexible, excellent damp heat performance on OSP treated copper. Same chemistry as DB-1541 DB-1588-1 Lowest cost, flexible, excellent damp heat performance on OSP treated copper. Same chemistry as DB-1588 Ci-1031-7 High thixotropy high aspect ratio / fine line print 1.5 x 10-5 75 12,000 Dispense 2 x 10-4 5 30,000 Stencil Print 4 x 10-4 5 30,000 Stencil Print 1.5 x 10-5 75 12,000 Screen Print Ci-1031-8 Low thixotropy Easiest to print 1.5 x 10-5 75 12,000 Screen Print	Low Cost Conductive Adhesives						
DB-1541-LTC Low temperature cure version (100C) for organic PV and other temperature sensitive modules Conductive Adhesives for Back Contact Applications Flexible, high peel strength, Damp heat stability on tin and OSP treated copper. Designed to cure during EVA lamination DB-1588 Low cost, flexible, excellent damp heat performance on OSP treated copper. Same chemistry as DB-1541 DB-1588-1 Lowest cost, flexible, excellent damp heat performance on OSP treated copper. Same chemistry as DB-1588 CI-1031-7 High thixotropy high aspect ratio / fine line print 1.5 x 10-5 75 20,000 Screen Print CI-1031-8 Low thixotropy Easiest to print 1.5 x 10-5 75 12,000 Screen Print	DB-1590		2 x 10-4	15	20,000	Dispense	
DB-1541-LTC Low temperature cure version (100C) for organic PV and other temperature sensitive modules Conductive Adhesives for Back Contact Applications Flexible, high peel strength, Damp heat stability on tin and OSP treated copper. Designed to cure during EVA lamination DB-1541 Low cost, flexible, excellent damp heat performance on OSP treated copper. Same chemistry as DB-1541 DB-1588 Lowest cost, flexible, excellent damp heat performance on OSP treated copper. Same chemistry as DB-1541 DB-1588-1 Lowest cost, flexible, excellent damp heat performance on OSP treated copper. Same chemistry as DB-1588 CI-1031-7 High thixotropy high aspect ratio / fine line print 1.5 x 10-5 75 20,000 Screen Print CI-1031-8 Low thixotropy Easiest to print 1.5 x 10-5 75 12,000 Screen Print	DB-1548-LC	Low cost version of DB-1548 series	9x 10-4	62	30,000	Dispense	
Conductive Adhesives for Back Contact Applications Flexible, high peel strength, Damp heat stability on tin and OSP treated copper. Designed to cure during EVA lamination DB-1588 Low cost, flexible, excellent damp heat performance on OSP treated copper. Same chemistry as DB-1541 DB-1588-1 Lowest cost, flexible, excellent damp heat performance on OSP treated copper. Same chemistry as DB-1588 Conductive Grid Inks CI-1031-7 High thixotropy high aspect ratio / fine line print Low thixotropy Easiest to print 1,5 x 10-5 17,000 17,000 17,000 17,000 17,000 17,000 17,000 10,	Low Temperature Cure Conductive Adhesives						
DB-1541 Flexible, high peel strength, Damp heat stability on tin and OSP treated copper. Designed to cure during EVA lamination DB-1588 Low cost, flexible, excellent damp heat performance on OSP treated copper. Same chemistry as DB-1541 DB-1588-1 Lowest cost, flexible, excellent damp heat performance on OSP treated copper. Same chemistry as DB-1588 Conductive Grid Inks CI-1031-7 High thixotropy high aspect ratio / fine line print 1.5 x 10-5 75 20,000 Screen Print CI-1031-8 Low thixotropy Easiest to print 1.5 x 10-5 75 12,000 Screen Print	DB-1541-LTC		2 x 10-4	50	17,000	Dispense	
DB-1541 and OSP treated copper. Designed to cure during EVA lamination DB-1588 Low cost, flexible, excellent damp heat performance on OSP treated copper. Same chemistry as DB-1541 DB-1588-1 Lowest cost, flexible, excellent damp heat performance on OSP treated copper. Same chemistry as DB-1588 CI-1031-7 High thixotropy high aspect ratio / fine line print 1.5 x 10-5 75 20,000 Screen Print CI-1031-8 Low thixotropy Easiest to print 1.5 x 10-5 75 12,000 Screen Print	Conductive	Adhesives for Back Contact Applications					
DB-1588 OSP treated copper. Same chemistry as DB-1541 4 x 10 ⁻⁴ 5 30,000 Stencil Print DB-1588-1 Lowest cost, flexible, excellent damp heat performance on OSP treated copper. Same chemistry as DB-1588 4 x 10-4 5 30,000 Stencil Print Conductive Grid Inks CI-1031-7 High thixotropy high aspect ratio / fine line print 1.5 x 10-5 75 20,000 Screen Print CI-1031-8 Low thixotropy Easiest to print 1.5 x 10-5 75 12,000 Screen Print	DB-1541	and OSP treated copper. Designed to cure during EVA	1 x 10-4	13	33,000	Stencil Print	
Conductive Grid Inks CI-1031-8 Low thixotropy Easiest to print CI-1031-8	DB-1588		4 x 10-4	5	30,000	Stencil Print	
CI-1031-7 High thixotropy high aspect ratio / fine line print 1.5 x 10-5 75 20,000 Screen Print CI-1031-8 Low thixotropy Easiest to print 1.5 x 10-5 75 12,000 Screen Print	DB-1588-1		4 x 10-4	5	30,000	Stencil Print	
CI-1031-8 Low thixotropy Easiest to print 1.5 x 10-5 75 12,000 Screen Print	Conductive Grid Inks						
	CI-1031-7	High thixotropy high aspect ratio / fine line print	1.5 x 10-5	75	20,000	Screen Print	
CI-1031-9 Low cost filler 2.5 x 10-5 80 17,000 Screen Print	CI-1031-8	Low thixotropy Easiest to print	1.5 x 10-5	75	12,000	Screen Print	
	CI-1031-9	Low cost filler	2.5 x 10-5	80	17,000	Screen Print	